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Docket No.: M4065.0248/P248-C  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of:  
Allen McTeer

Application No.: 10/656,182

Confirmation No.: 8422

Filed: September 8, 2003

Art Unit: 2815

For: A MULTI-LAYERED COPPER BOND PAD  
FOR AN INTEGRATED CIRCUIT

Examiner: E. Lee

**REQUEST FOR RECONSIDERATION**

MS Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**INTRODUCTORY COMMENTS**

In response to the Office Action dated July 14, 2005, please reconsider the above-identified U.S. patent application in view of the following remarks: